CALL FOR PAPERS
March 25-28, 2021 | Osaka, Japan

AMSE 2021
The 3rd International Conference on Advanced Materials Science and Engineering

Topics
- Composite Materials and Repairs
- Energy Materials and Composites
- Materials Characteristics
- Metals and Alloys
- Nanomaterials
- Smart Materials and Systems
- Surface Engineering and Tribology
- Laser, Microwave and Thermal Processing
- Biomaterials, Tissue Engineering
- Ceramics
- Fracture of Materials
- Building Materials

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02 Submission
Submission Link: http://confsys.iconf.org/submission/amse2021
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Abstract Format: http://amse.net/files/abstract.docx

03 Proceedings
Accepted papers will be published in Conference Proceedings only after presentation during the conference, which will be sent for major indexing.

04 Important Dates
Submission Deadline: February 10th, 2021
Acceptance Notification: February 20th, 2021
Registration Deadline: March 05th, 2021

Contact
Ms. Maggie X.Xu
E-mail: amse_secretary@yeah.net
Tel.: +86 180 8007 5398 (EN & CN)